



Material Content Data Sheet



Sales Product Name		IPD90N03S4L-03		Issued		1. August 2018		
MA#		MA001659458						
Package		PG-TO252-3-11		Weight*		370.61 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.247	0.61	0.61	6063	6063
leadframe	inorganic material	phosphorus	7723-14-0	0.065	0.02		174	
	non noble metal	iron	7439-89-6	0.215	0.06		581	
	non noble metal	copper	7440-50-8	215.017	58.02	58.10	580170	580925
	non noble metal	aluminium	7429-90-5	4.109	1.11	1.11	11087	11087
wire	non noble metal	aluminium	7429-90-5	4.109	1.11	1.11	11087	11087
encapsulation	organic material	carbon black	1333-86-4	1.238	0.33		3340	
	plastics	epoxy resin	-	21.664	5.85		58454	
	inorganic material	silicondioxide	60676-86-0	100.890	27.22	33.40	272228	334022
leadfinish	non noble metal	tin	7440-31-5	3.740	1.01	1.01	10092	10092
plating	inorganic material	phosphorus	7723-14-0	0.000	0.00		1	
	non noble metal	nickel	7440-02-0	0.091	0.02	0.02	245	246
solder	non noble metal	tin	7440-31-5	0.043	0.01		115	
	noble metal	silver	7440-22-4	0.053	0.01		144	
	non noble metal	lead	7439-92-1	2.035	0.55	0.57	5492	5751
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		16	
	non noble metal	iron	7439-89-6	0.019	0.01		52	
	non noble metal	copper	7440-50-8	19.177	5.17	5.18	51746	51814
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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